

Features

- ANODE-Common Structure(Dual TVS)
- Suitable to small packages (SOT-23) Chip Size=0.53mmsq
- High ESD protection level
IEC61000-4-2(ESD) +/-16kV(Air) +/-9kV(Contact)

Applications

- Computers and Peripherals
- Communication systems
- Audio and video equipment
- Parallel ports

Item	Characteristics
Wafer size	5inch
Chip size	530*530um

Maximum Ratings (Ta=25degC)

Symbol	Parameter	Value	Units
P _{pk}	Peak Power Dissipation(tp=8/20us) (*1)	300	W
I _{pp}	Maximum Peak Pulse Current(tp=8/20us) (*1)	18.5	A
T _{stg}	Storage Temperature Range	-55 to+150	Deg C
T _j	Maximum Junction Temperature (*1)	150	Deg C
V _{pp}	Electrostatic Discharge IEC61000-4-2 Air Discharge (*1) IEC61000-4-2 Contact Discharge (*1)	±16 ±9	kV kV

(*1) Rating value for reference on a SOT-23 package configuration (front: Au wire 35um, back: Au eutectic), mounted on PCB of 1.5cm by 2.5cm.

Electrical Characteristics (Ta=25degC)

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Breakdown Voltage	V _{BR}	6.1	6.65	7.2	V	I _R =1.0mA
Leakage Current	I _{RM}	-	-	2.5	uA	V _{RM} =5.25V
Capacitance	C	-	140	-	pF	0V 1MHz
Forward Voltage Drop	V _F	-	-	1.25	V	I _F =200mA
Clamping Voltage	V _c	-	-	16.2	V	I _{pp} =18.5A *1

*1 Package=SOT-23(front: Au wire 35um, back: Au eutectic)